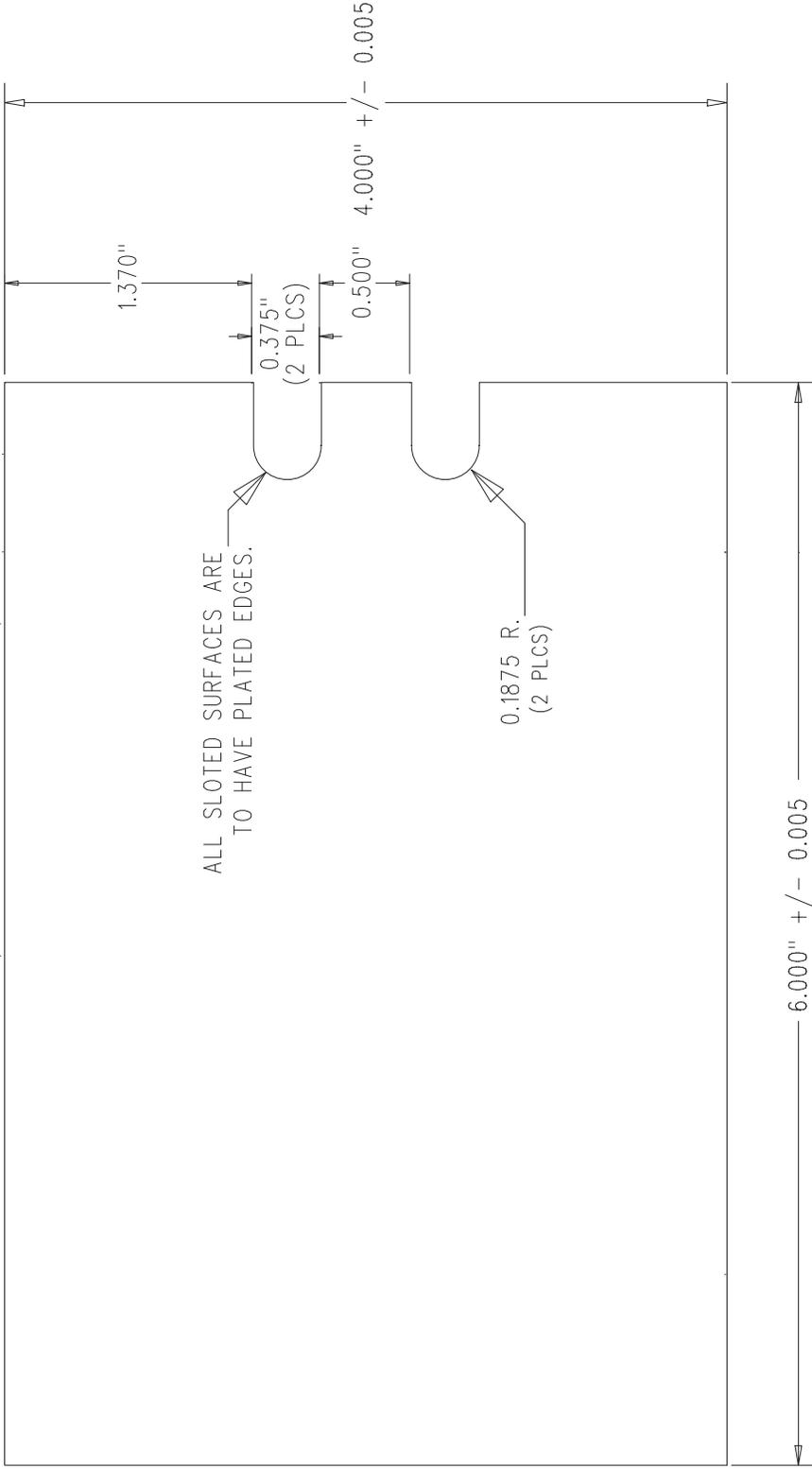


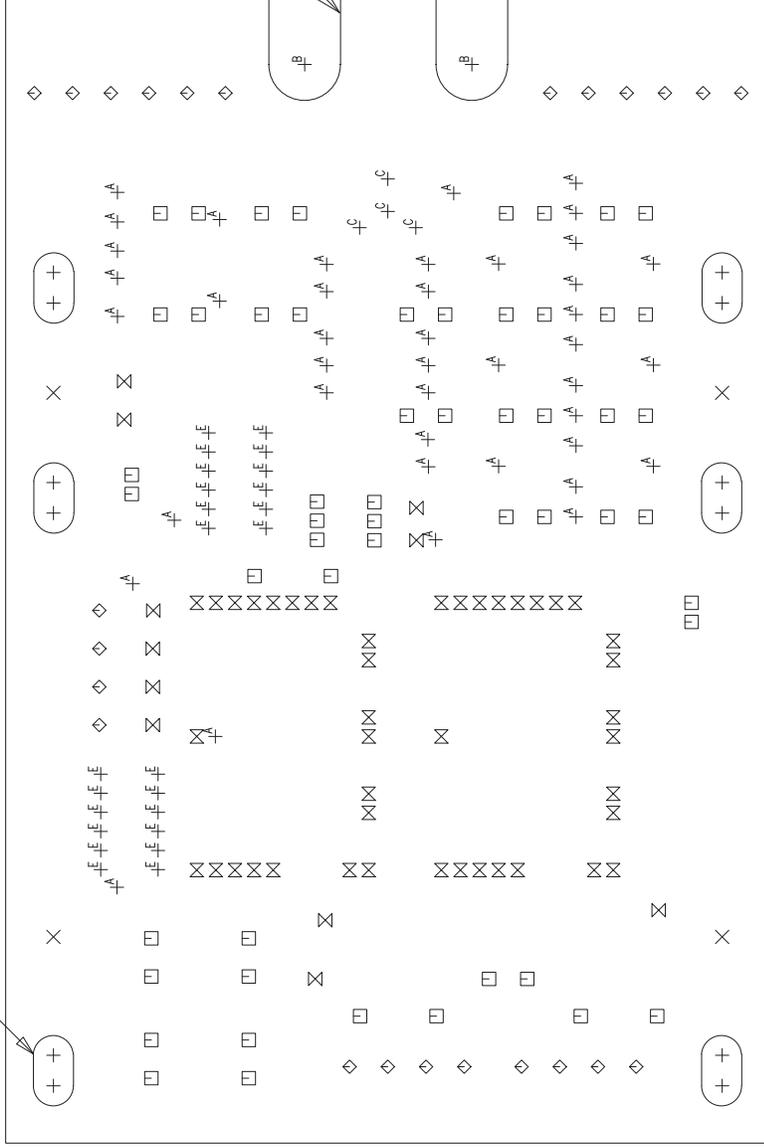
Reference TI Document 87-00020 for Quality Assurance Requirements
 All Dimensions are in Inches +/-0.005 Unless Otherwise Specified.



Substrate material: Grade FR-406 UL certified 94V-0, ≥ 170°C Tg
 Circuitry material: Copper (2 oz), Finished on all layers
 and thickness: 0.062" +/- 0.005"
 Overall thickness: Entek CU-106 A
 Protective finish: In the bottom side solder mask
 Vendor marking: White non-conductive
 Legend: Green liquid photo-imageable (LPI) on both sides, SMOBC
 Solder mask:

 27715 Diehl Road, Warrenville, IL. 60555	TIDA-00582	DESCRIPTION PCB, FR-406, PTH08T250 EVALUATION BOARD		DWG NO 74-00828
	FILENAME 828-1C.PCB	DRAWN DATE	REV 1C	ECO NUMBER
	CHECKED DATE	SIZE A	SCALE 1:1	
	ISSUED DATE	DO NOT SCALE DRAWING		PAGE 1 OF 9

-.200 X .360 PLATED SLOT (6 PLCS)



ROUTED PLATED SLOT (2 PLCS)

FINISHED HOLE SIZES
Dimensions are in Inches

SIZE	QTY	SYM	PLATED	TOL
0.2	12	+	YES	+/-0.003
0.159	4	X	NO	+/-0.002
0.04	54	□	YES	+/-0.003
0.052	24	◇	YES	+/-0.003
0.063	11	⊗	YES	+/-0.003
0.055	44	⊗	YES	+/-0.003
0.02	42	+A	YES	+0.003/-0.010
0.375	2	- ^B	YES	+/-0.003
0.072	4	- ^C	YES	+/-0.003
0.045	24	- ^E	YES	+/-0.003

TIDA-00582



DESCRIPTION

PCB, FR-406, PTH08T250 EVALUATION BOARD

DWG NO

74-00828

REV

1C

FILENAME

828-1C.PCB

SIZE

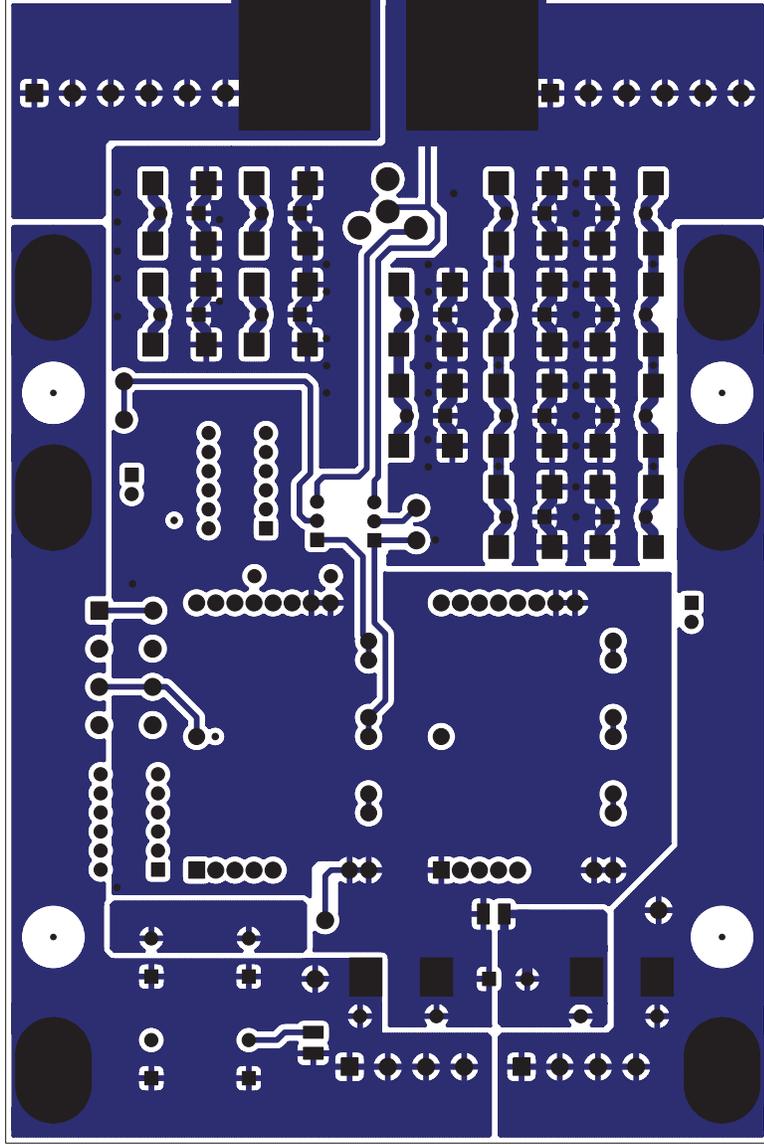
A

SCALE

1:1

DO NOT SCALE DRAWING

PAGE 2 OF 9



COMPONENT SIDE METAL

TIDA-00582

DESCRIPTION

PCB, FR-406, PTH08T250 EVALUATION BOARD

SIZE

A

SCALE

1:1

DO NOT SCALE DRAWING

PAGE 3 OF 9

DWG NO

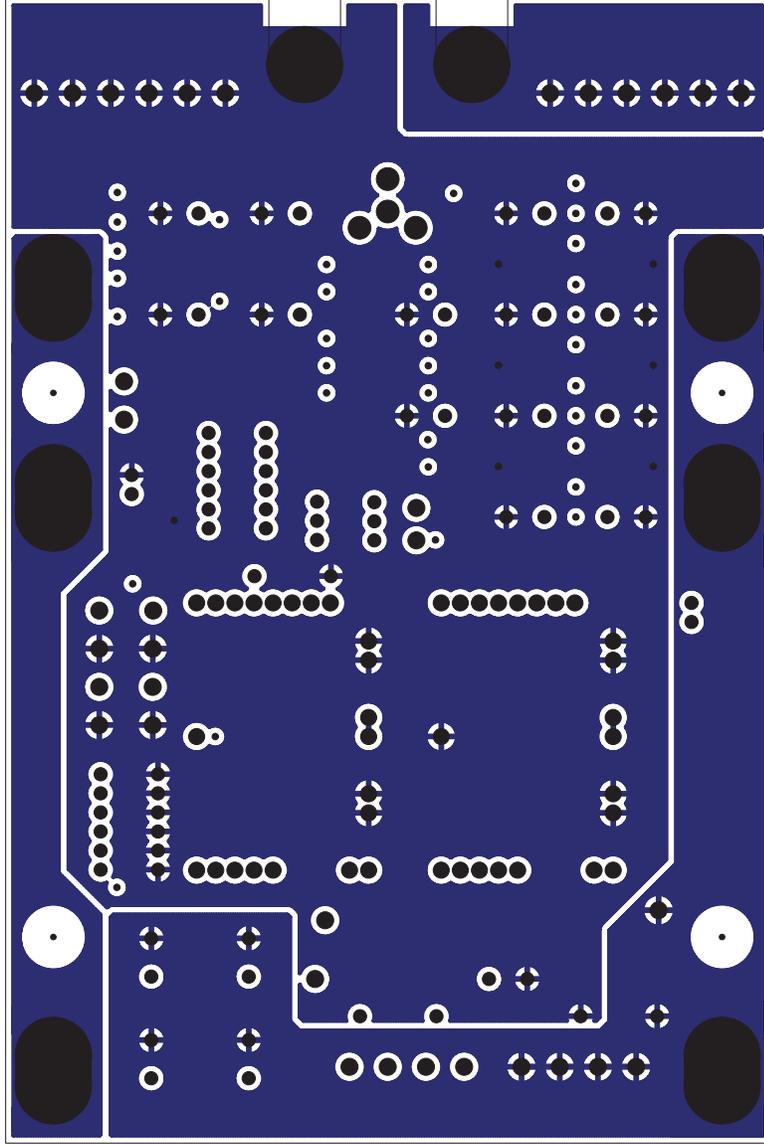
74-00828

REV

1C

FILENAME

828-1C.PCB



LAYER 2 METAL

TIDA-00582

DESCRIPTION

PCB, FR-406, PTH08T250 EVALUATION BOARD

DWG NO

74-00828

REV

1C

FILENAME

828-1C.PCB

SIZE

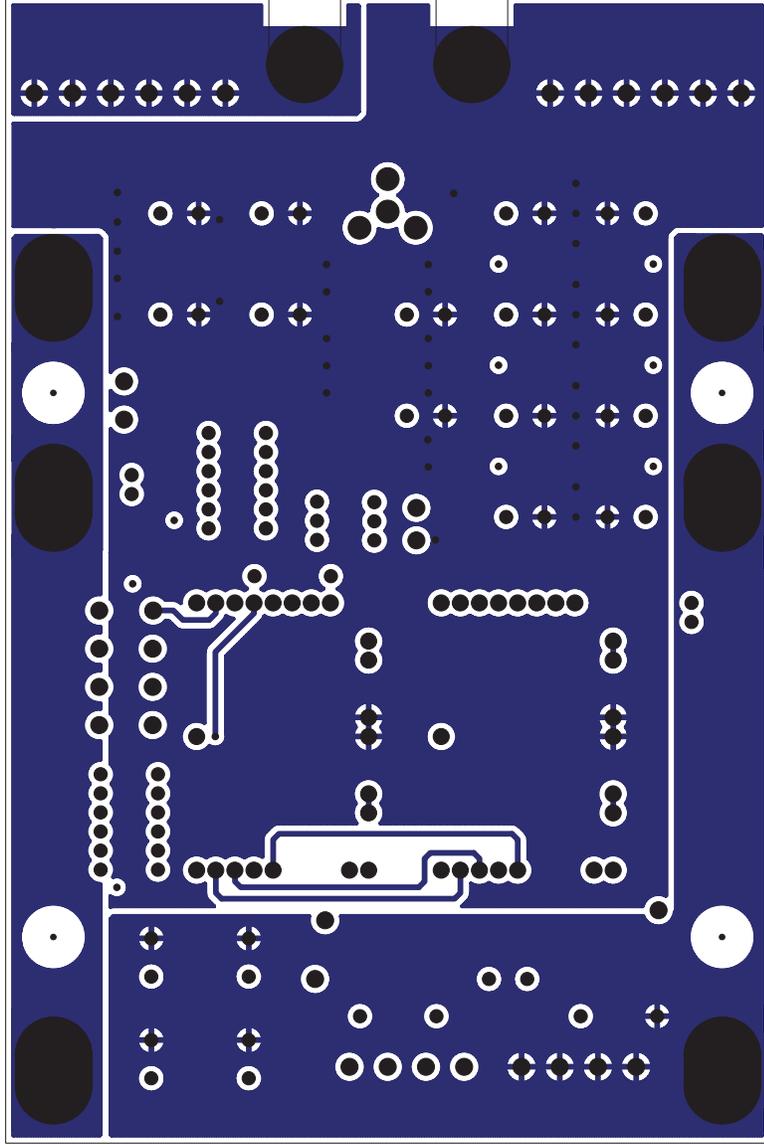
A

SCALE

1:1

DO NOT SCALE DRAWING

PAGE 4 OF 9



LAYER 3 METAL

TIDA-00582

DESCRIPTION

PCB, FR-406, PTH08T250 EVALUATION BOARD

DWG NO

74-00828

REV

1C

FILENAME

828-1C.PCB

SIZE

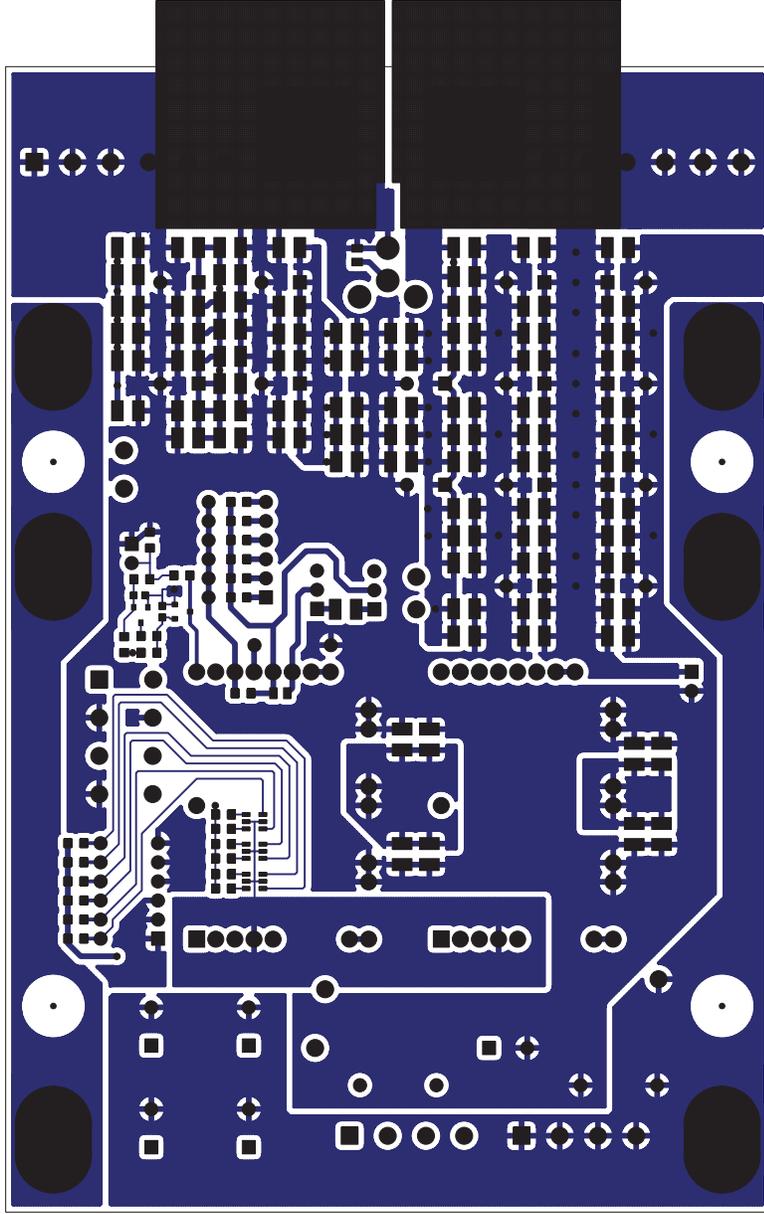
A

SCALE

1:1

DO NOT SCALE DRAWING

PAGE 5 OF 9



SOLDER SIDE METAL

TIDA-00582

DESCRIPTION

PCB, FR-406, PTH08T250 EVALUATION BOARD

SIZE

A

SCALE

1:1

DWG NO

74-00828

REV

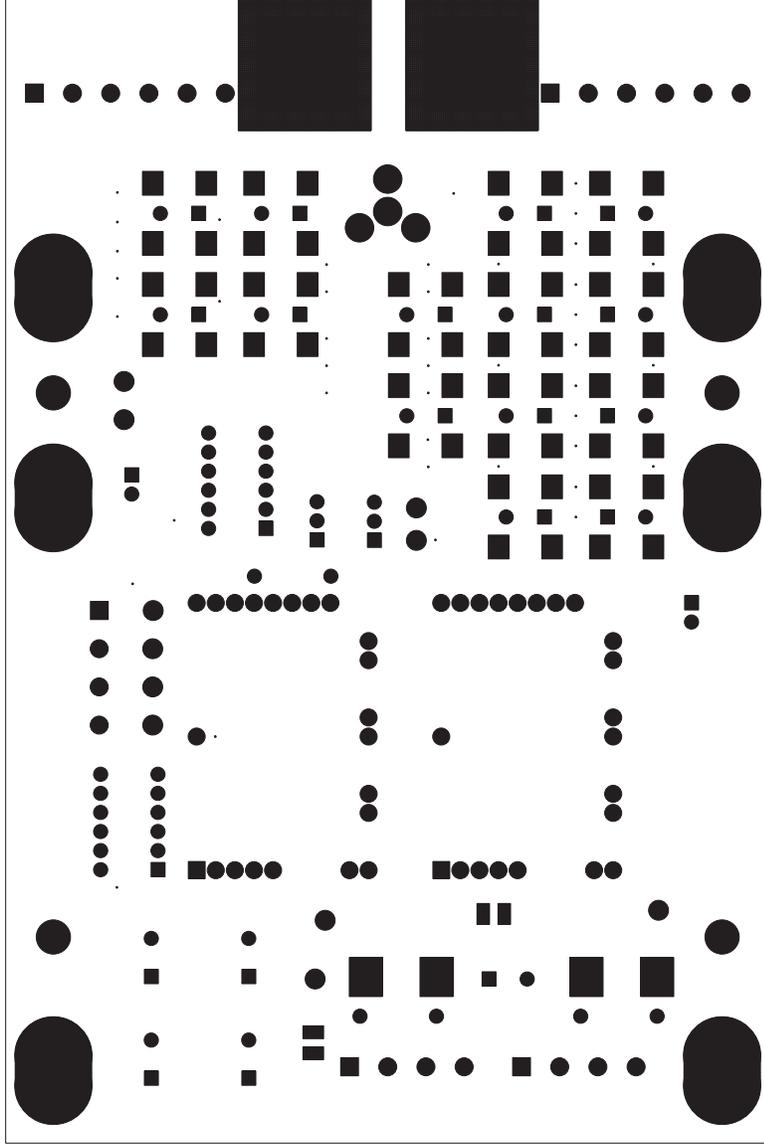
1C

FILENAME

828-1C.PCB

DO NOT SCALE DRAWING

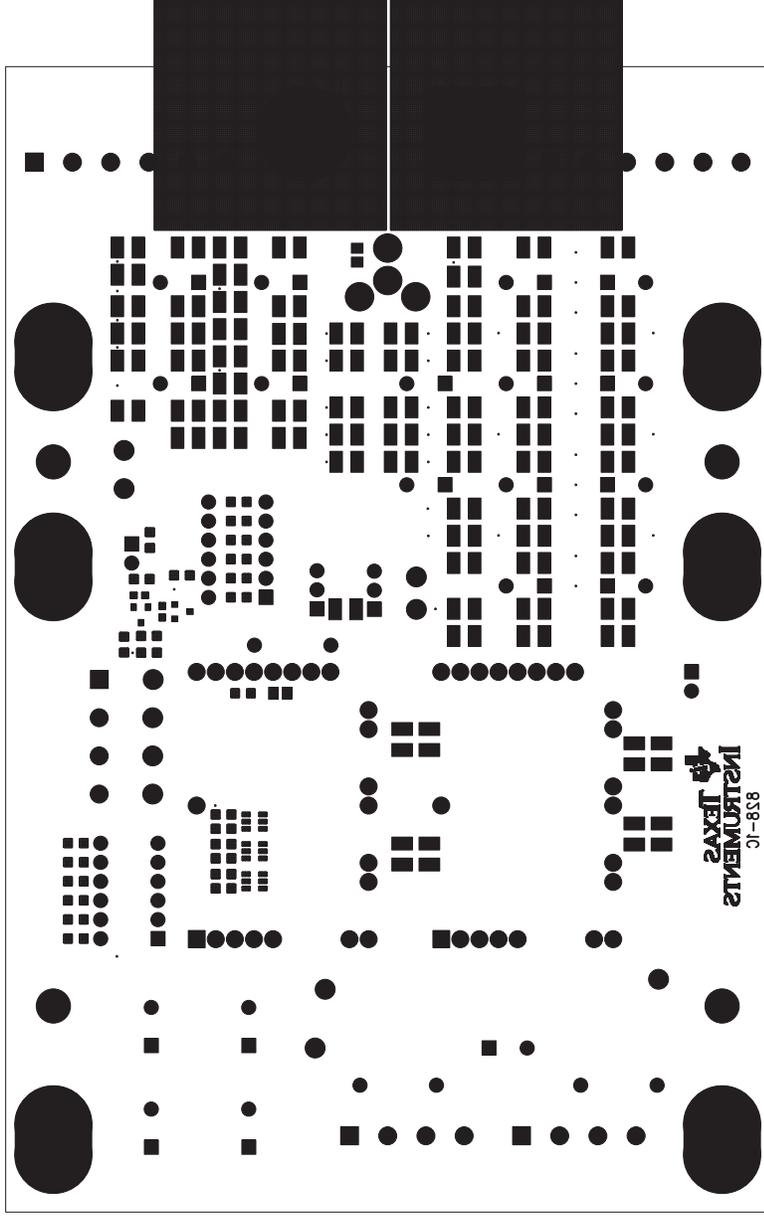
PAGE 6 OF 9



COMPONENT SIDE SOLDER MASK

Areas shown above are solder mask openings.
 Use Liquid Photo-Imageable solder mask for mask shown above.
 Thickness of Liquid Solder Mask on top of circuit traces must not exceed 0.002"

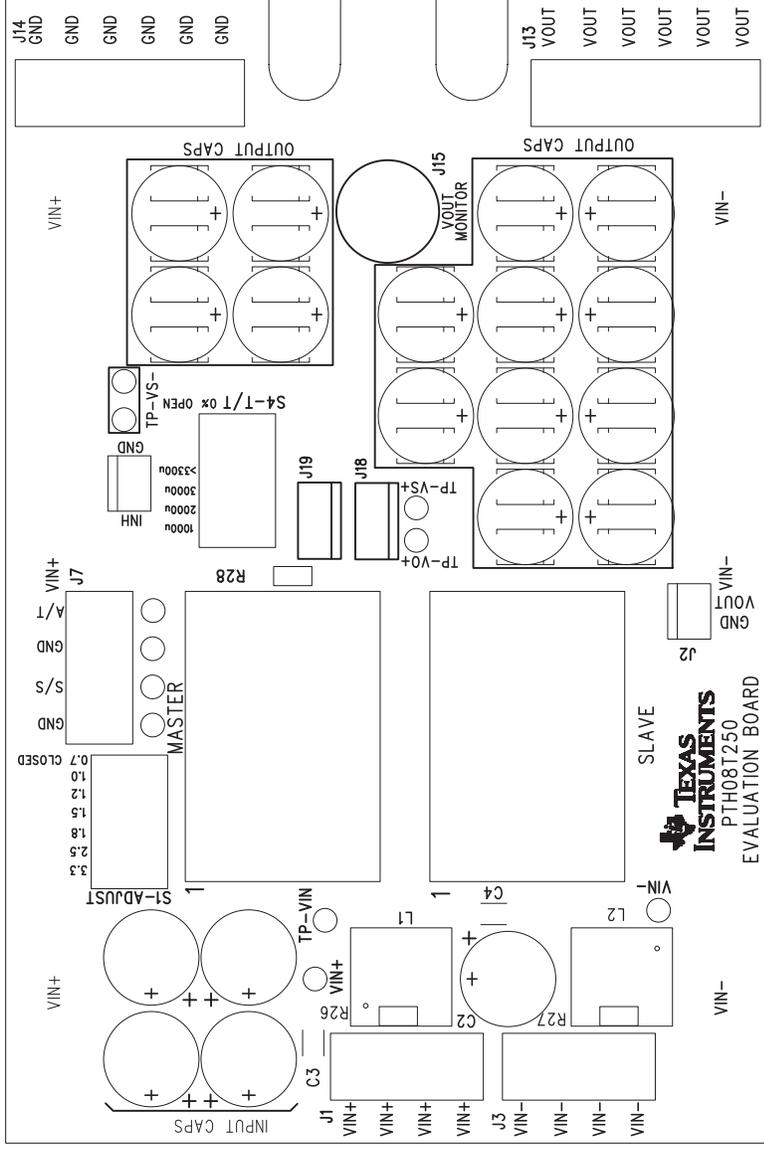
TIDA-00582	DESCRIPTION		SIZE	SCALE
	PCB, FR-406, PTH08T250 EVALUATION BOARD		A	1:1
	DWG NO	REV	FILENAME	DO NOT SCALE DRAWING
	74-00828	1C	828-1C.PCB	PAGE 7 OF 9



SOLDER SIDE SOLDER MASK

Areas shown above are solder mask openings.
 Use Liquid Photo-Imageable solder mask for mask shown above.
 Thickness of Liquid Solder Mask on top of circuit traces must not exceed 0.002"

 27715 Diehl Road, Warrenville, IL 60555	TIDA-00582	DESCRIPTION		SIZE	SCALE
		PCB, FR-406, PTH08T250 EVALUATION BOARD	A	1:1	
	DWG NO	REV	FILENAME	DO NOT SCALE DRAWING	
	74-00828	1C	828-1C.PCB	PAGE	8 OF 9



TOP SIDE SILK SCREEN

 27715 Diehl Road, Warrenville, IL 60555	TIDA-00582	DESCRIPTION PCB, FR-406, PTH08T250 EVALUATION BOARD	
	9 OF 9	PAGE	SCALE
9 OF 9	PAGE	SCALE	1:1
DO NOT SCALE DRAWING	DO NOT SCALE DRAWING	A	A
REV	REV	FILENAME	SCALE
1C	1C	828-1C.PCB	9 OF 9
74-00828	74-00828	828-1C.PCB	9 OF 9

IMPORTANT NOTICE FOR TI REFERENCE DESIGNS

Texas Instruments Incorporated ("TI") reference designs are solely intended to assist designers ("Buyers") who are developing systems that incorporate TI semiconductor products (also referred to herein as "components"). Buyer understands and agrees that Buyer remains responsible for using its independent analysis, evaluation and judgment in designing Buyer's systems and products.

TI reference designs have been created using standard laboratory conditions and engineering practices. **TI has not conducted any testing other than that specifically described in the published documentation for a particular reference design.** TI may make corrections, enhancements, improvements and other changes to its reference designs.

Buyers are authorized to use TI reference designs with the TI component(s) identified in each particular reference design and to modify the reference design in the development of their end products. HOWEVER, NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY THIRD PARTY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT, IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI REFERENCE DESIGNS ARE PROVIDED "AS IS". TI MAKES NO WARRANTIES OR REPRESENTATIONS WITH REGARD TO THE REFERENCE DESIGNS OR USE OF THE REFERENCE DESIGNS, EXPRESS, IMPLIED OR STATUTORY, INCLUDING ACCURACY OR COMPLETENESS. TI DISCLAIMS ANY WARRANTY OF TITLE AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, QUIET ENJOYMENT, QUIET POSSESSION, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS WITH REGARD TO TI REFERENCE DESIGNS OR USE THEREOF. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY BUYERS AGAINST ANY THIRD PARTY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON A COMBINATION OF COMPONENTS PROVIDED IN A TI REFERENCE DESIGN. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, SPECIAL, INCIDENTAL, CONSEQUENTIAL OR INDIRECT DAMAGES, HOWEVER CAUSED, ON ANY THEORY OF LIABILITY AND WHETHER OR NOT TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES, ARISING IN ANY WAY OUT OF TI REFERENCE DESIGNS OR BUYER'S USE OF TI REFERENCE DESIGNS.

TI reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques for TI components are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

Reproduction of significant portions of TI information in TI data books, data sheets or reference designs is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards that anticipate dangerous failures, monitor failures and their consequences, lessen the likelihood of dangerous failures and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in Buyer's safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed an agreement specifically governing such use.

Only those TI components that TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components that have **not** been so designated is solely at Buyer's risk, and Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.